# - GSMBSS1391

# **GSMBSS139K**

## **60V N-Channel MOSFETs**

## **Product Description**

These N-Channel Enhancement Mode Power Field Effect Transistors are Using Trench DMOS Technology. This Advanced Technology has been Especially Tailored to Minimize on-state Resistance, Provide Superior Switching Performance, and Withstand high Energy Pulse in the Avalanche and Commutation mode.

These Devices are well Suited for High Efficiency Fast Switching Applications.

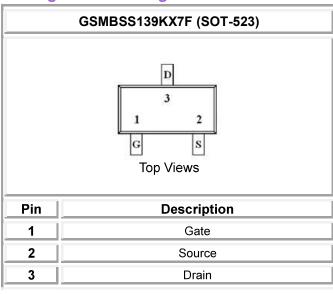
#### **Features**

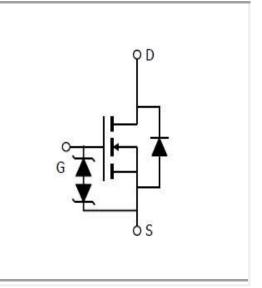
- 60V, 0.2A,  $R_{DS(ON)}$ =2.5 $\Omega$ @ $V_{GS}$ =4.5V
- Improved dv/dt Capability
- Fast Switching
- Green Device Available
- SOT-523 Package Design
- ESD Protected: 1500V

## **Applications**

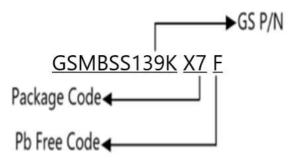
- Notebook
- Load Switch
- LED Applications

## **Packages & Pin Assignments**



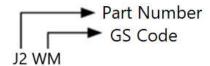


## **Ordering Information**





## **Marking Information**



| Part Number   | Package | Part Marking | Quantity |  |
|---------------|---------|--------------|----------|--|
| GSMBSS139KX7F | SOT-523 | J2WM         | 3000pcs  |  |

# Absolute Maximum Ratings T<sub>A</sub>=25°C Unless otherwise noted

| Symbol           | Parameter   | Limits      | Unit                 |
|------------------|---|-------------|----------------------|
| V <sub>DS</sub>  | Drain-Source Voltage  | 60          | V                    |
| V <sub>GS</sub>  | Gate-Source Voltage   | ±20         | V                    |
| l <sub>D</sub>   | Continuous Drain Current T <sub>A</sub> =25°C                     | 0.2         | Α                    |
| Ірм              | Pulsed Drain Current  | 0.8         | Α                    |
| В                | Power Dissipation (T <sub>A</sub> =25°ℂ)                          | 0.225       | W                    |
| P <sub>D</sub>   | Power Dissipation (Derate above 25℃)                              | 0.0018      | W/°C                 |
| TJ               | Operating Junction Temperature Range                              | -55 to +150 | $^{\circ}\mathbb{C}$ |
| T <sub>STG</sub> | Storage Temperature Range   | -55 to +150 | $^{\circ}\mathbb{C}$ |
| R <sub>eJA</sub> | Thermal Resistance-Junction to Ambient                            | 556         | °C/W                 |
| TL               | Maximum Lead Temperature for Soldering<br>Purpose, for 10 Seconds | 260         | °C                   |

## **Electrical Characteristics**

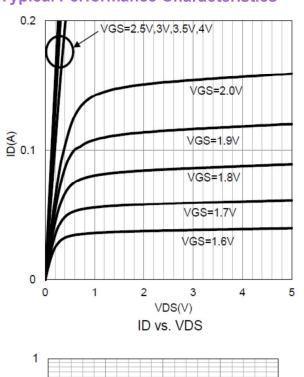
T<sub>A</sub>=25°C Unless otherwise noted

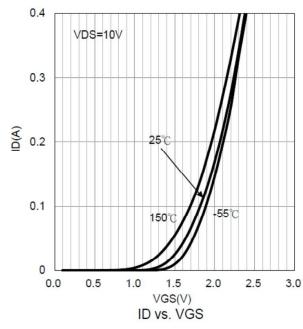
| Symbol               | Parameter                       | Conditions  | Min  | Тур | Max  | Unit    |  |
|----------------------|---------------------------------|---|------|-----|------|---------|--|
|                      | Static                          |   |      |     |      |         |  |
| V <sub>(BR)DSS</sub> | Drain-Source Breakdown Voltage  | V <sub>GS</sub> =0V,I <sub>D</sub> =250uA               | 60   | -   | -    | V       |  |
| $V_{GS(th)}$         | Gate Threshold Voltage          | V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250uA | 0.85 | -   | 1.45 | V       |  |
| IGSSF                | Gate Leakage Current , Forward  | V <sub>DS</sub> =0V,V <sub>GS</sub> =20V                |      |     | 10   | $\mu$ A |  |
| Igssr                | Gate Leakage Current , Reverse  | V <sub>DS</sub> =0V,V <sub>GS</sub> =-20V               |      |     | -10  | $\mu$ A |  |
|                      | Zero Gate Voltage Drain Current | V <sub>DS</sub> =25V,V <sub>GS</sub> =0V                |      |     | 0.1  |         |  |
| IDSS                 |                                 | V <sub>DS</sub> =50V,V <sub>GS</sub> =0V,               |      |     | 0.5  | uA      |  |
| П                    | Drain-Source On-Resistance      | V <sub>GS</sub> =4.5V,I <sub>D</sub> =0.2A              |      | -   | 2.25 |         |  |
| R <sub>DS(on)</sub>  |                                 | V <sub>GS</sub> =2.5V,I <sub>D</sub> =0.1A              |      | -   | 4.05 | Ω       |  |
| <b>g</b> FS          | Forward Transconductance        | V <sub>DS</sub> =25V,I <sub>D</sub> =0.2A               | 100  | _   | _    | mS      |  |

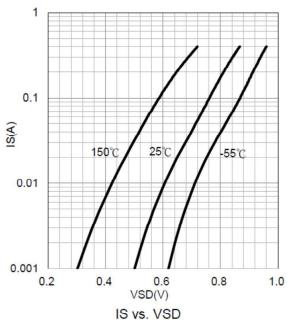


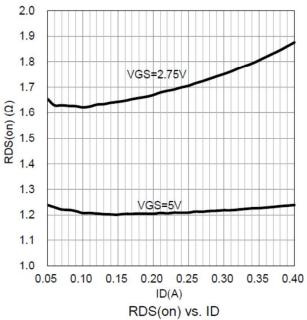
|                     | Dynamic                      |  |      |     |
|---------------------|------------------------------|--|------|-----|
| Ciss                | Input Capacitance            |  | 22.8 |     |
| Coss                | Output Capacitance           | $V_{DS}$ =25V, $V_{GS}$ =0V,<br>f=1MHz   | 3.5  | pF  |
| Crss                | Reverse Transfer Capacitance |  | 2.9  |     |
| t <sub>d(on)</sub>  | Turn-On Time                 | V <sub>DD</sub> =30V,I <sub>D</sub> =1A, | 3.8  | ns  |
| t <sub>d(off)</sub> | Turn-Off Time                | $V_{GS}$ =10V, $R_{G}$ =25 $\Omega$      | 19   | 113 |

## **Typical Performance Characteristics**

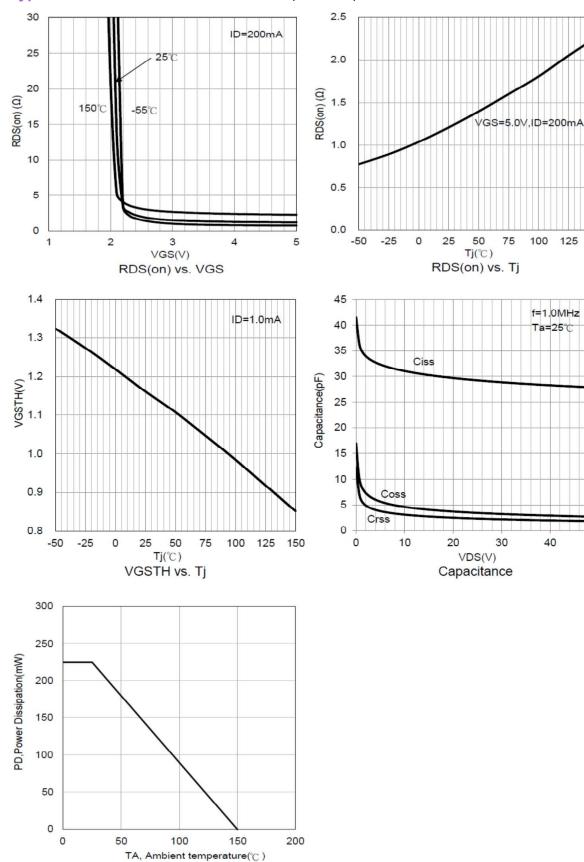








## **Typical Performance Characteristics (Continue)**





Power Dissipation vs Ambient temperature

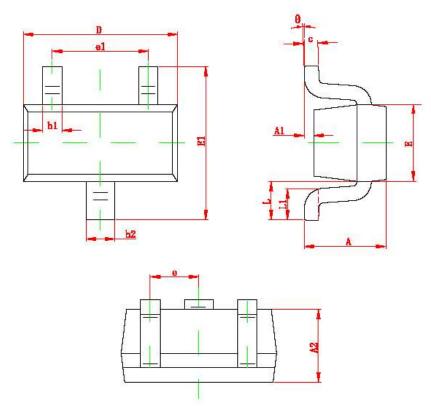
125

150

50

# **Package Dimension**

# **SOT-523**



|            | Dimensions            |       |            |       |  |
|------------|-----------------------|-------|------------|-------|--|
| Symbol     | Millimeters           |       | Inches     |       |  |
|            | Min                   | Max   | Min        | Max   |  |
| Α          | 0.700                 | 0.900 | 0.028      | 0.035 |  |
| <b>A</b> 1 | 0.000                 | 0.100 | 0.000      | 0.004 |  |
| A2         | 0.700                 | 0.800 | 0.028      | 0.031 |  |
| b1         | 0.150                 | 0.250 | 0.006      | 0.010 |  |
| b2         | 0.250                 | 0.350 | 0.010      | 0.013 |  |
| С          | 0.100                 | 0.200 | 0.004      | 0.008 |  |
| D          | 1.500                 | 1.700 | 0.059      | 0.067 |  |
| E          | 0.700                 | 0.900 | 0.028      | 0.035 |  |
| E1         | 1.450                 | 1.750 | 0.057      | 0.069 |  |
| е          | 0.500(TYP) 0.020(TYP) |       | (TYP)      |       |  |
| e1         | 0.900                 | 1.100 | 0.035      | 0.043 |  |
| L          | 0.550(REF)            |       | 0.022(REF) |       |  |
| L1         | 0.280                 | 0.440 | 0.011      | 0.017 |  |
| θ          | 0°                    | 8°    | 0°         | 8°    |  |



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